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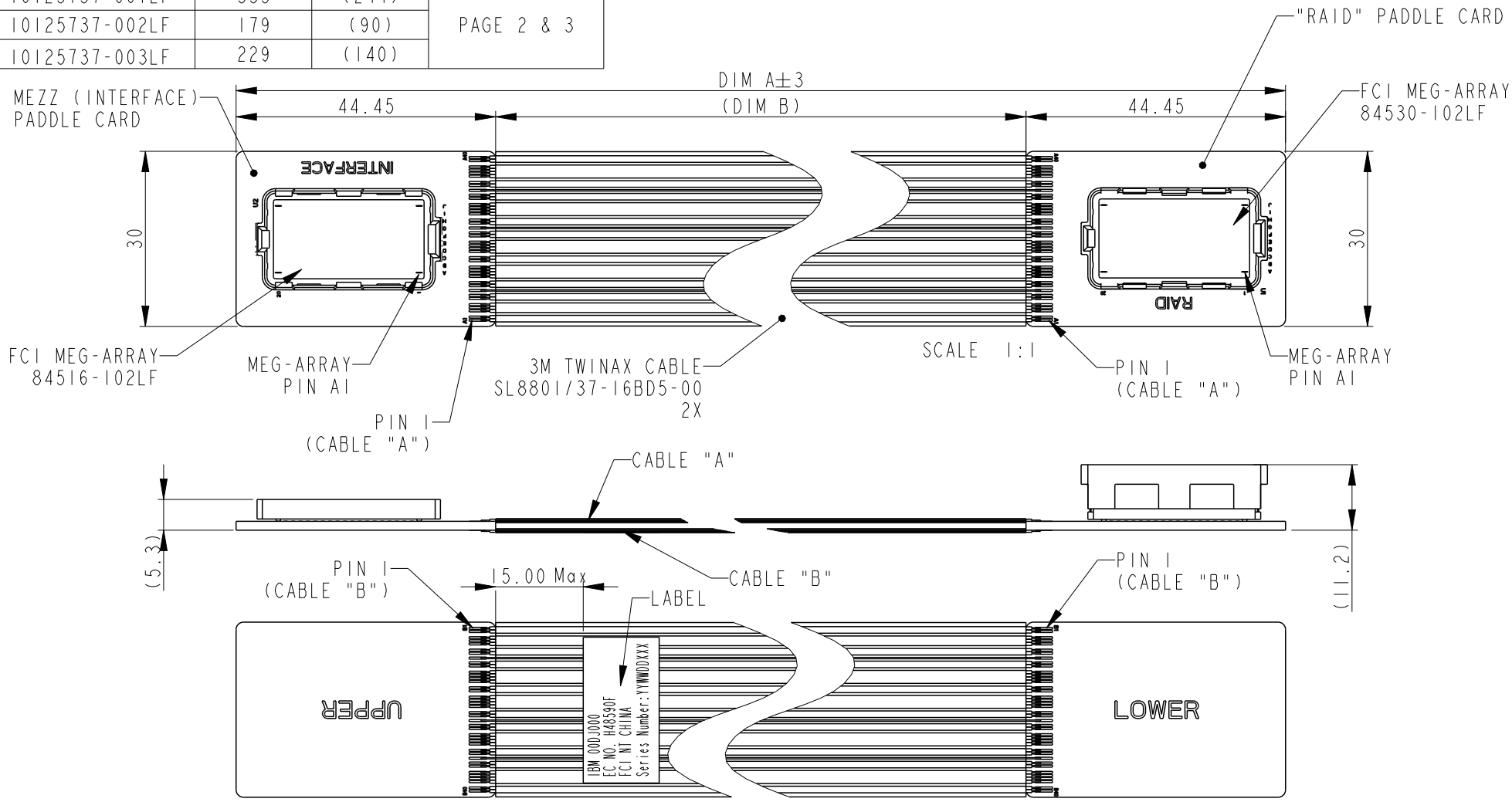
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

PRODUCT NUMBER	DIM A	(DIM B)	PIN ASSIGNMENT
10125737-001LF	333	(244)	PAGE 2 & 3
10125737-002LF	179	(90)	
10125737-003LF	229	(140)	



spec ref			dr	Kenny Tai	2013/06/19	projection	mm
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED		eng	Ya Li	2014/03/05		
			chr	-	-		
			appr	Delhly Liu	2014/03/05	product family	-
surface -	linear	0.X	±.3	FCI	title	PADDLE CARDS ASSEMBLY	dwg no 10125737
		0.XX	±.15			MEG-ARRAY CABLE ASSEMBLY	rev D
		0.XXX	±	www.fci.com	cat. no.	10125737	Product - Customer Drw
	angular	0°	±°				sheet 1 of 4

size A4 | scale 1:5 | ecn no ELX-N-17093-1 | rel level Released

RAID MegArray	RAID TwinAx Lower	"A" Cable (same side as MegArray)	MEZZ TwinAx Upper	MEZZ MegArray
	P1	Pin Description	**P2**	
A7	A1	HS_PCIE16_RAID_TX_IF_RX_3_N	A1	A5
B7	A2	HS_PCIE16_RAID_TX_IF_RX_3_P	A2	B5
Plane Shape	A3	SE_12V0	A3	Plane Shape
Plane Shape	A4	SE_GND	A4	Plane Shape
I4	A5	LS_RAID_IF_DEVICE_DIS_1_N	A5	I17
C8	A6	HS_PCIE16_RAID_TX_IF_RX_2_N	A6	C6
D8	A7	HS_PCIE16_RAID_TX_IF_RX_2_P	A7	D6
Plane Shape	A8	GND	A8	Plane Shape
A9	A9	HS_PCIE16_RAID_TX_IF_RX_1_N	A9	A7
B9	A10	HS_PCIE16_RAID_TX_IF_RX_1_P	A10	B7
Plane Shape	A11	SE_GND	A11	Plane Shape
Plane Shape	A12	SE_12V0	A12	Plane Shape
Plane Shape	A13	SE_12V0	A13	Plane Shape
Plane Shape	A14	SE_GND	A14	Plane Shape
C10	A15	HS_PCIE16_RAID_TX_IF_RX_0_N	A15	C8
D10	A16	HS_PCIE16_RAID_TX_IF_RX_0_P	A16	D8
D3	A17	LS_IF_RAID_PRESENCE_OUT_N	A17	B18
H3	A18	LS_RAID_IF_ALL_PGOOD	A18	H18
I3	A19	LS_IF_RAID_PGOOD	A19	I18
C2	A20	LS_IF_RAID_AUXPGOOD	A20	C19
C20	A21	HS_RAID_IF_PCIE_REFCLK1_N	A21	C18
D20	A22	HS_RAID_IF_PCIE_REFCLK1_P	A22	D18
Plane Shape	A23	GND	A23	Plane Shape
G5	A24	HS_PCIE16_IF_TX_RAID_RX_0_P	A24	G1
H5	A25	HS_PCIE16_IF_TX_RAID_RX_0_N	A25	H1
Plane Shape	A26	SE_GND	A26	Plane Shape
Plane Shape	A27	SE_12V0	A27	Plane Shape
B2	A28	LS_RAID_IF_LEDPWR	A28	B19
H2	A29	LS_RAID_IF_ERR_LED_CATHODE	A29	H19
I6	A30	HS_PCIE16_IF_TX_RAID_RX_1_P	A30	I2
J6	A31	HS_PCIE16_IF_TX_RAID_RX_1_N	A31	J2
Plane Shape	A32	GND	A32	Plane Shape
G7	A33	HS_PCIE16_IF_TX_RAID_RX_2_P	A33	G3
H7	A34	HS_PCIE16_IF_TX_RAID_RX_2_N	A34	H3
Plane Shape	A35	SE_GND	A35	Plane Shape
Plane Shape	A36	SE_3V3	A36	Plane Shape
Plane Shape	A37	SE_GND	A37	Plane Shape
C3	A38	LS_IF_RAID_BIFURCATE_N	A38	A18
I8	A39	HS_PCIE16_IF_TX_RAID_RX_3_P	A39	I4
J8	A40	HS_PCIE16_IF_TX_RAID_RX_3_N	A40	J4

RAID MegArray	RAID TwinAx Lower	"B" Cable	MEZZ TwinAx Upper	MEZZ MegArray
	P1	Pin Description	**P2**	
A3	B1	HS_PCIE16_RAID_TX_IF_RX_7_N	B1	A1
B3	B2	HS_PCIE16_RAID_TX_IF_RX_7_P	B2	B1
Plane Shape	B3	SE_12V0	B3	Plane Shape
Plane Shape	B4	SE_GND	B4	Plane Shape
G2	B5	LS_RAID_IF_PCIE_RESET_N	B5	G19
C4	B6	HS_PCIE16_RAID_TX_IF_RX_6_N	B6	C2
D4	B7	HS_PCIE16_RAID_TX_IF_RX_6_P	B7	D2
Plane Shape	B8	GND	B8	Plane Shape
A5	B9	HS_PCIE16_RAID_TX_IF_RX_5_N	B9	A3
B5	B10	HS_PCIE16_RAID_TX_IF_RX_5_P	B10	B3
Plane Shape	B11	SE_GND	B11	Plane Shape
Plane Shape	B12	SE_3V3	B12	Plane Shape
G1	B13	LS_RAID_IF_SLOT_ID_0	B13	G20
H1	B14	LS_RAID_IF_SLOT_ID_1	B14	H20
C6	B15	HS_PCIE16_RAID_TX_IF_RX_4_N	B15	C4
D6	B16	HS_PCIE16_RAID_TX_IF_RX_4_P	B16	D4
G3	B17	LS_IF_RAID_I2C_INT_N	B17	G18
D1	**B18**	**LS_RAID_IF_I2C_RESET_N**	**B18**	**D20**
E1	B19	LS_RAID_IF_I2C_SDA	B19	E20
F1	B20	LS_RAID_IF_I2C_SCL	B20	F20
G9	B21	HS_PCIE16_IF_TX_RAID_RX_4_P	B21	G5
H9	B22	HS_PCIE16_IF_TX_RAID_RX_4_N	B22	H5
Plane Shape	B23	GND	B23	Plane Shape
I10	B24	HS_PCIE16_IF_TX_RAID_RX_5_P	B24	I6
J10	B25	HS_PCIE16_IF_TX_RAID_RX_5_N	B25	J6
Plane Shape	B26	SE_GND	B26	Plane Shape
Plane Shape	B27	SE_12V0	B27	Plane Shape
H4	B28	LS_RAID_IF_PRESENCE_IN_N	B28	H17
Plane Shape	B29	SE_GND	B29	Plane Shape
G11	B30	HS_PCIE16_IF_TX_RAID_RX_6_P	B30	G7
H11	B31	HS_PCIE16_IF_TX_RAID_RX_6_N	B31	H7
Plane Shape	B32	GND	B32	Plane Shape
I12	B33	HS_PCIE16_IF_TX_RAID_RX_7_P	B33	I8
J12	B34	HS_PCIE16_IF_TX_RAID_RX_7_N	B34	J8
Plane Shape	B35	SE_GND	B35	Plane Shape
Plane Shape	B36	SE_12V0	B36	Plane Shape
Plane Shape	B37	SE_12V0	B37	Plane Shape
Plane Shape	B38	SE_GND	B38	Plane Shape
Test Point	B39	DIFF_RSRVD	B39	Test Point
Test Point	B40	DIFF_RSRVD	B40	Test Point

NOTE:
1. SEE PAGE 3 FOR "PLANE SHAPE".
2. "A1", "A2" OF "TwinAx"... MEAN WIRES OF CABLE "A"
3. "B1", "B2" OF "TwinAx"... MEAN WIRES OF CABLE "B"

PIN ASSIGNMENT

dr	Kenny Tai	2013/06/19
eng	Ya Li	2014/03/05
chr	-	-
appr	Delhly Liu	2014/03/05

projection | mm | size A4 | scale 1:1

ecn no ELX-N-17093-1

product family -

rel level **Released**

title: PADDLE CARDS ASSEMBLY
MEG-ARRAY CABLE ASSEMBLY

dwg no 10125737

rev **D**

www.fci.com | cat. no. 10125737 | Product - Customer Drw | sheet 2 of 4

RAID MegArray		Mezz MegArray
I1 I2 J1 J2 J3	SE_12V0 Plane Shape	I19 I20 J18 J19 J20
A1 A2	SE_3V3 Plane Shape	A19 A20
A4,A6,A8,A10,A12,A14,A16,A18,A20, B4,B6,B8,B10,B12,B14,B16,B18,B20 , C5,C7,C9,C11,C13,C15,C17,C19, D5,D7,D9,D11,D13,D15,D17,D19, E2-E20 F2, F5-F20 G4,G6,G8,G10,G12,G14,G16,G18,G20,H6,H8, H10,H12,H14,H16,H18,H20, I5,I7,I9, I11,I13, I15, I17, I19 J5,J7,J9, J11,J13, J15,J17, J19	GND Plane Shape	A2, A4, A6, A8, A10, A12, A14, A16, B2, B4, B6, B8, B10, B12, B14, B16, C1,C3,C5, C7,C9, C11,C13,C15,C17 D1,D3,D5, D7,D9, D11,D13,D15,D17, E1-E19, F1-F16, F18,F19 G2, G4, G6, G8, G10, G12, G14, G16, H2, H4, H6, H8, H10, H12, H14, H16, I1,I3,I5, I7,I9, I11,I13, I15, J1,J3,J5, J7,J9, J11, J13,J15
Same as GND	SE_GND Plane Shape	Same as GND
J4	Floating pins	J17

PLANE SHAPE

dr	Kenny Tai	2013/06/19	projection	mm	size A4	scale 1:1
eng	Ya Li	2014/03/05			ecn no	ELX-N-17093-1
chr	-	-			rel level	Released
appr	Delhly Liu	2014/03/05	product family	-		

FCI

title: PADDLE CARDS ASSEMBLY
MEG-ARRAY CABLE ASSEMBLY

dwg no: 10125737

rev: D

www.fci.com | cat. no. 10125737 | Product - Customer Drw | sheet 3 of 4

Pro/E File - REV C - 2009-06-09

NOTE:
1.The electrical requirements, at the assembly level, as follows: (0-2ns is test vehicle)
1.1 Differential Impedance: 100ps (20-80%)
  RAID PI Side 14mm stack height.
    - 2.0 to 2.6 ns 80 to 130 ohms
    - 2.6 to 4.0 ns 70 to 115 ohms
  Interface P2 Side 4mm stack height.
    - 2.0 to 2.5 ns 75 to 120 ohms
    - 2.5 to 4.0 ns 70 to 115 ohms
1.2 Single-end Impedance 100ps (20-80%)
  RAID PI Side 14mm stack height - AVE Single Ended Impedance not to exceed .
    - 2.0 to 2.6 ns 45 to 85 ohms
    - 2.6 to 4.0 ns 45 to 65 ohms
  Interface P2 Side 4mm stack height - AVE Ended Impedance not to exceed .
    - 2.0 to 2.5 ns 45 to 70 ohms
    - 2.5 to 4.0 ns 45 to 65 ohms
1.3 Differential Insertion loss of finished assembly without test board loss
   -4.3 dB   @ 1.5GHz
   -7.6 dB   @ 3 GHz
   -15.4 dB @ 5 GHz
   -30 dB   @ 8 GHz
   -41 dB   @ 10 GHz
1.4 Maximum paddle card thickness = 50 mils
1.5 Maximum paddle card via stub length = 15 mils
1.6 Raw Twinax conductors must be 32 Gauge
1.7 There must be no fewer than four (4) discrete GND "sideband" wire connections within the raw 3M twinax cable
1.8 All sidebands must be tied to a common GND plane at each paddle card.
2. Package specification: GS-14-2352
3. Pin to Pin Resistance not allow to exceed 2 ohms - HiPot test: 300V dc - 2 Mega-ohms - 10ms .
4. The detail of the label: IBM P/N: 00DJ000;IBM EC NUMBER: H48590F;FCI Location:FCT NT CHINA;
   Series Number:YYMMDDXXX.

dr	Kenny Tai	2013/06/19	projection	mm	size A4 / scale 1:10
eng	Ya Li	2014/03/05			
chr	-	-			ecn no ELX-N-17093-1
appr	Delhly Liu	2014/03/05	product family -		rel level Released

www.fci.com	title: PADDLE CARDS ASSEMBLY MEG-ARRAY CABLE ASSEMBLY	dwg no 10125737	rev D
	cat. no. -	Product - Customer Drw	sheet 4 of 4

Pro/E File - REV C - 2009-06-09